



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

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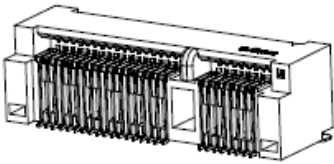


- Connectors
- Sockets / Edgecards
- Cable Assemblies
- Antennas
- Fiber Optic Products
- Printed Circuit Products
- Automation / Industrial
- Lighting Products

Home:

Part Number: 48338-0090

MINI PCI EXP. 0.8MM PITCH



Series image - Reference only

Status: Planned for Obsolescence

Series: 48338
Category: Molex Parts

Go to [Part Detail](#)

CHECK DISTRIBUTOR INVENTORY

[Add to My Parts](#)

Specifications & Other Documents:

Documents not available online

Note - Please disable browser pop-up blockers to view documents on [www.molex.com](#)

Product Environmental Compliance

Questions on Product Environmental Compliance? Email productcompliance@molex.com

[EU RoHS](#): ELV and RoHS Compliant

[China RoHS](#):

[REACH SVHC](#): Contains SVHC: No

[Low-Halogen Status](#): Low-Halogen



Product Compliance Statement

Application Tooling

[FAQ](#)

Tooling specifications and manuals are found by selecting the products below.

Crimp Height Specifications are then contained in the Application Tooling Specification document.

Previously Available Application Tooling

[Check our list of old tooling that used to be available for this part](#)

Part Detail

COLLAPSE ALL

General

Status	Planned for Obsolescence
Category	Molex Parts
Series	48338
UPC	883906571252

Physical

Net Weight	2.266/g
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Solder Process Data

Duration at Max. Process Temperature (seconds)	8
Lead-free Process Capability	Reflow Capable (SMT only)
Max. Cycles at Max. Process Temperature	1
Process Temperature max. C	260

Material Info

Molex Connectors

Wire-to-Board
Board-to-Board
Wire-to-Wire
Input/Output (IO)
FFC/FPC
Sockets

Other Products

Fiber Optic Products
Antennas
Industrial Automation
Membrane Switches
Copper Flex
PCB Assemblies
Woodhead Electrical
Solid State Lighting

Resources

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